

RF ESD Protection Diodes

ESD protection of RF antenna /

interfaces or ultra high speed data lines acc. to:

IEC61000-4-2 (ESD): ± 15 KV (air / contact)

IEC61000-4-4 (EPT): 40 A (5/50 ns)

IEC61000-4-5 (surge): 5 A (8/20 μs)

Very low line capacitance: 0.4 pF @ 1 GHz
 (0.2 pF per diode)



Very low clamping voltage

Ultra small leadless package: 1.2 x 0.8 x 0.39 mm³

• Pb-free (RoHS compliant) package

Applications in anti-parallel configuration

 For low RF signal levels without superimposed DC voltage: e.g. GPS, XM-Radio, Sirius, DVB, DMB, DAB, Remote Keyless Entry

Applications in rail-to-rail configuration

 For high RF signal levels or low RF signal levels with superimposed DC voltage: e.g. HDMI, S-ATA, Gbit Ethernet



ESD0P4RFL



Туре	Package	Configuration	Marking
ESD0P4RFL	TSLP-4-7	anti-parallel	E4





Maximum Ratings at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
ESD contact discharge ¹⁾	V _{ESD}	15	kV
Peak pulse current $(t_p = 8 / 20 \mu s)^2$	I _{pp}	5	А
Operating temperature range	Top	-55150	°C
Storage temperature	$T_{ m stg}$	-65150	

Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values		Unit	
		min.	typ.	max.	
Characteristics -	·			•	
Reverse working voltage ³⁾	V_{RWM}	_	-	50	V
Reverse current ³⁾	I _R	-	20	100	nA
V _R = 50 V					
Forward clamping voltage ²⁾	V_{FC}	-	6	9	V
I _{PP} = 5 A					
Diode capacitance ⁴⁾	C _T	-	0.4	-	pF
$V_{R} = 0 \text{ V}, f = 1 \text{ GHz}$					
Series inductance per diode	L _S	-	0.4	-	nH

¹V_{ESD} according to IEC61000-4-2, only valid in anti-parallel or rail-to-rail connection.

Please refer to the application examples.

 $^{^2}I_{\mbox{\footnotesize pp}}$ according to IEC61000-4-5, only valid in anti-parallel or rail-to-rail connection.

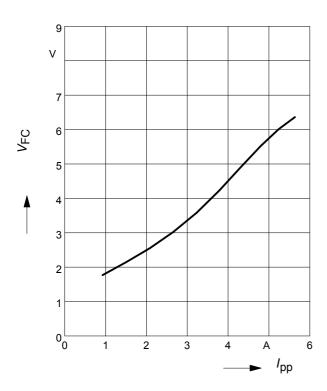
Please refer to the application examples.

 $^{^3}$ Only valid in rail-to-rail configuration with $V_{\rm CC} \le V_{\rm RWM}$

⁴Total capacitance line to ground (2 diodes in parallel)

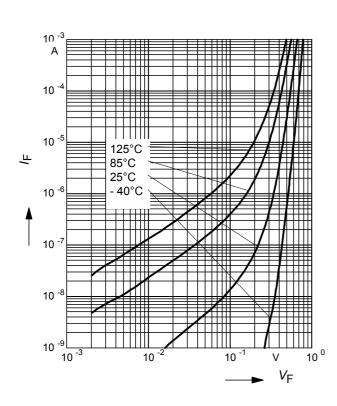


Forward clamping voltage V_{FC} = $f(I_{PP})$ t_p = 8 / 20 µs



Forward current $I_F = f(V_F)$

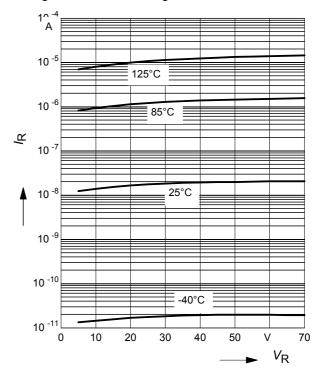
leakage in anti-parallel configuration



Reverse current $I_R = f(V_R)$

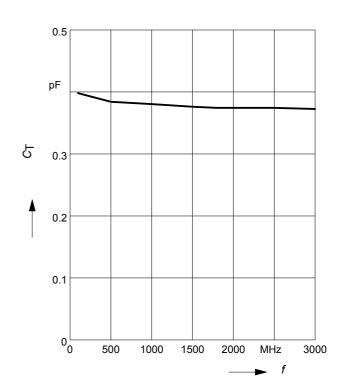
 T_A = Parameter

leakage in rail-to-rail configuration



Line capacitance $C_T = f$ (f)

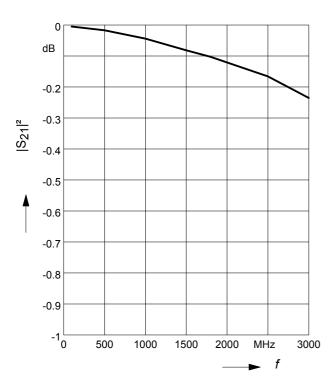
$$V_R = 0 V$$





Insertion loss $I_{L} = -|S_{21}|^2 = f(f)$

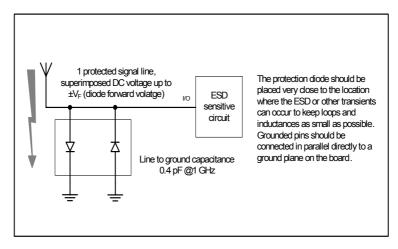
$$V_{\mathsf{R}}$$
 = 0 V, Z = 50 Ω





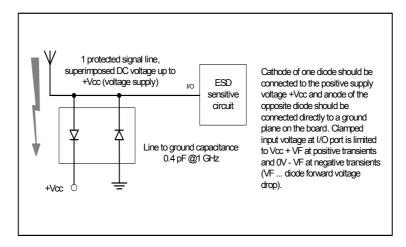
1. Application example ESD0P4RFL

1 RF signal channel, anti-parallel configuration



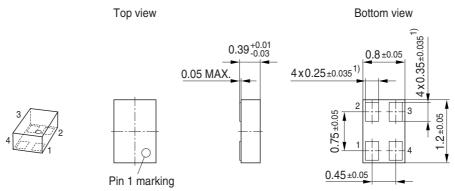
2. Application example ESD0P4RFL

1 RF signal channel, rail-to-rail configuration





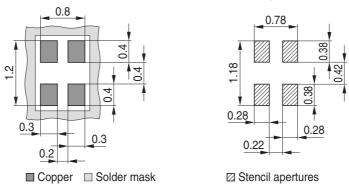
Package Outline



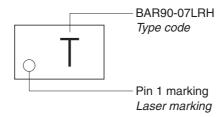
1) Dimension applies to plated terminal

Foot Print

For board assembly information please refer to Infineon website "Packages"

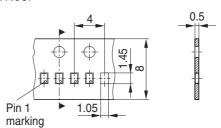


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



2011-06-27



Edition 2009-11-16

Published by Infineon Technologies AG 81726 Munich, Germany

© 2009 Infineon Technologies AG All Rights Reserved.

Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

Information

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (<www.infineon.com>).

Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

单击下面可查看定价,库存,交付和生命周期等信息

>>Infineon(英飞凌)